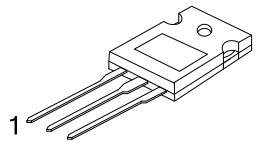
50NM65-F

Power MOSFET

50A, 650V N-CHANNEL SUPER-JUNCTION MOSFET



TO-247

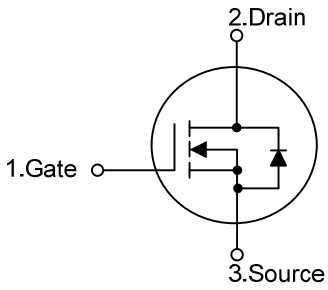
■ DESCRIPTION

The **UTC 50NM65-F** is a Super Junction MOSFET Structure and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and a high rugged avalanche characteristics. This power MOSFET is usually used at DC-DC, AC-DC converters for power applications.

■ FEATURES

* $R_{DS(ON)}$ < 90mΩ @ V_{GS}=10V, I_D=25A
* High Switching Speed
* With 100% Avalanche Tested

■ SYMBOL



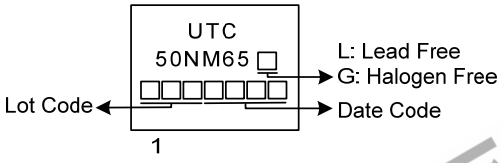
■ ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
50NM65L-T47-T	50NM65G-T47-T	TO-247	G	D	S	Tube

Note: Pin Assignment: G: Gate D: Drain S: Source

50NM65G-T47-T (1)Packing Type	(1) T: Tube
(2)Package Type	(2) T47: TO-247
(3)Green Package	(3) G: Halogen Free and Lead Free, L: Lead Free

■ MARKING



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■ ABSOLUTE MAXIMUM RATINGS (T_C =25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	650	V
Gate-Source Voltage		V_{GSS}	±30	V
Drain Current	Continuous	I_D	50	A
	Pulsed (Note 2)	I_{DM}	100	A
Avalanche Energy	Single Pulsed (Note 3)	E_{AS}	1550	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	4	V/ns
Power Dissipation		P_D	390	W
Junction Temperature		T_J	+150	°C
Storage Temperature Range		T_{STG}	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating : Pulse width limited by maximum junction temperature.
3. L=132mH, I_{AS}=2.33A, V_{DD}= 50V, R_G=25Ω, Starting T_J=25°C
4. I_{SD} ≤50A, di/dt ≤200A/μs, V_{DD} ≤BV_{DSS}, Starting T_J=25°C

■ THERMAL DATA

PARAMETER	SYMBOL	RATING	UNIT
Junction to Ambient	$θ_{JA}$	40	°C/W
Junction to Case	$θ_{JC}$	0.32	°C/W

■ ELECTRICAL CHARACTERISTICS (T_J=25°C, unless otherwise specified)

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV_{DSS}	V_{GS}=0V, I_D=250μA	650			V
Drain-Source Leakage Current		I_{DSS}	V_{DS}=650V, V_{GS}=0V			10	μA
Gate-Source Leakage Current	Forward	I_{GSS}	V_{DS}=0V ,V_{GS}=30V			100	nA
	Reverse		V_{DS}=0V ,V_{GS}=-30V			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		$V_{GS(TH)}$	V_{DS}= V_{GS}, I_D=250μA	2.5		4.5	V
Drain-Source On-State Resistance		$R_{DS(ON)}$	V_{GS}=10V, I_D=25A			90	mΩ
DYNAMIC PARAMETERS							
Input Capacitance		C_{ISS}	V_{GS}=0V, V_{DS}=25V, f=1.0MHz		3864		pF
Output Capacitance		C_{OSS}			2468		pF
Reverse Transfer Capacitance		C_{RSS}			160		pF
SWITCHING PARAMETERS							
Total Gate Charge (Note 1)		Q_G	V_{DS}=300V, V_{GS}=10V, I_D=30A , I_G=1mA (Note 1, 2)		122		nC
Gate to Source Charge		Q_{GS}			26		nC
Gate to Drain Charge		Q_{GD}			44		nC
Turn-ON Delay Time (Note 1)		$t_{D(ON)}$	V_{DD}=300V, V_{GS}=10V, I_D=30A, R_G=25Ω (Note 1, 2)		48		ns
Rise Time		t_R			38		ns
Turn-OFF Delay Time		$t_{D(OFF)}$			440		ns
Fall-Time		t_F			180		ns
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS							
Maximum Body-Diode Continuous Current		I_S				50	A
Maximum Body-Diode Pulsed Current		I_{SM}				100	A
Drain-Source Diode Forward Voltage (Note 1)		V_{SD}	I_S =50A, V_{GS}=0V			1.4	V
Body Diode Reverse Recovery Time (Note 1)		t_{rr}	I_S=30A, V_{GS}=0V, dI_F/dt=100A/μs		380		ns
Body Diode Reverse Recovery Charge		Q_{rr}			5.5		μC

Notes: 1. Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2%.
2. Essentially independent of operating temperature.

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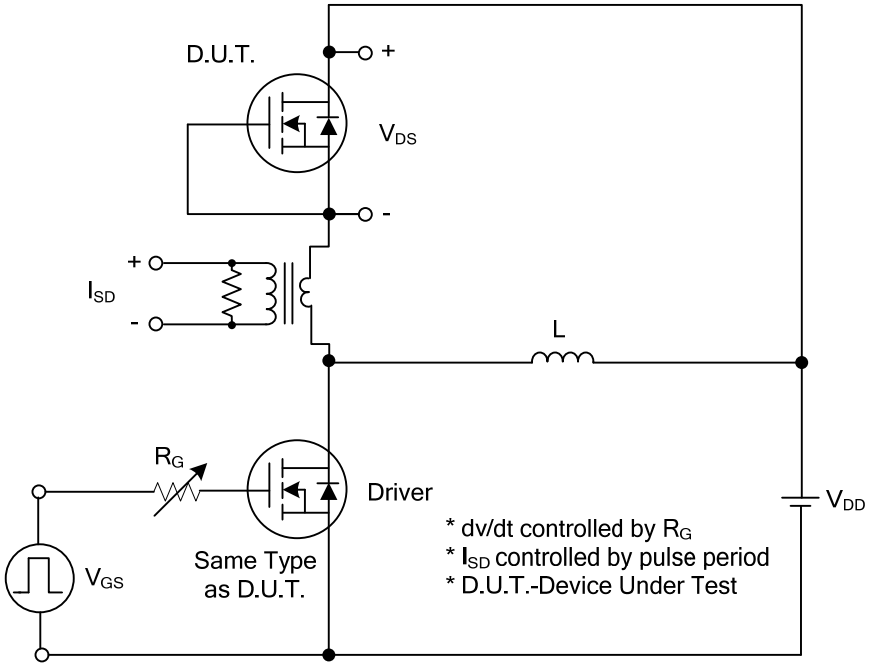
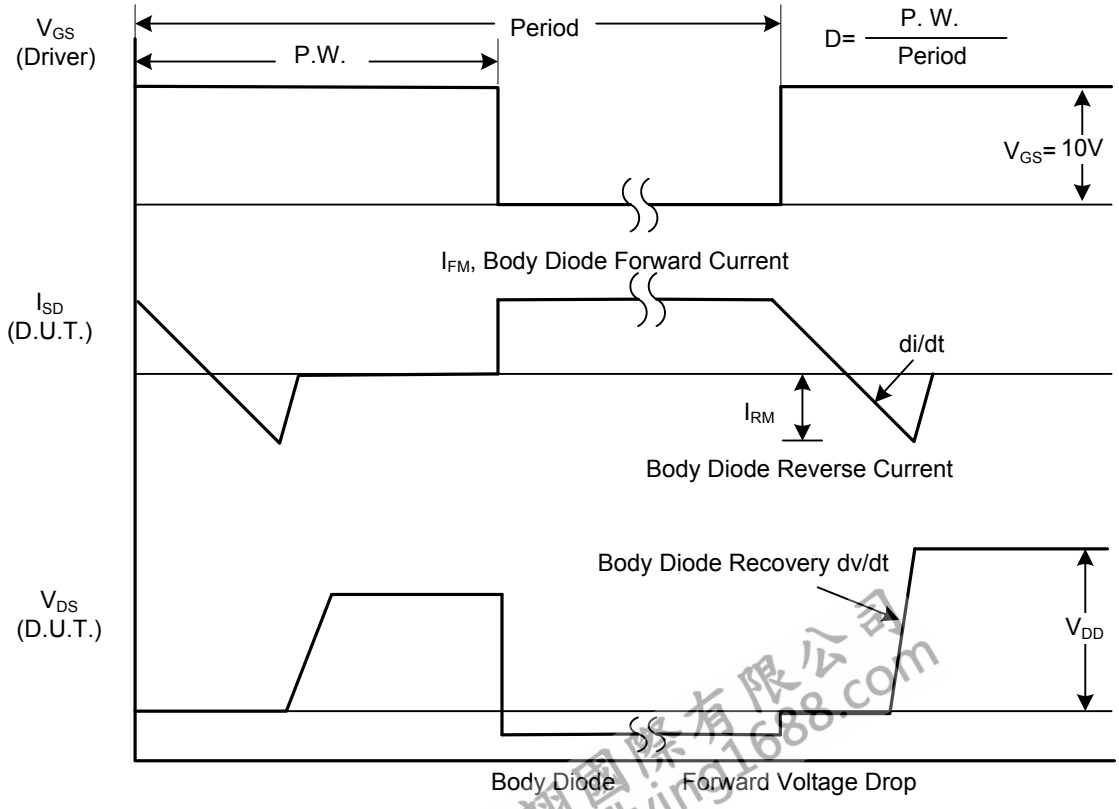
■ TEST CIRCUITS AND WAVEFORMS



Peak Diode Recovery dv/dt Test Circuit



Peak Diode Recovery dv/dt Waveforms

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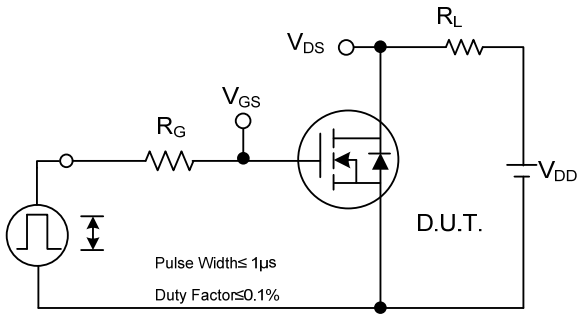
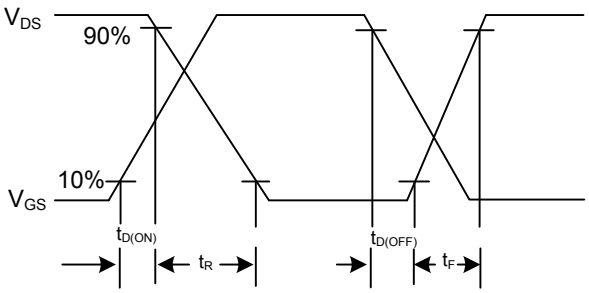
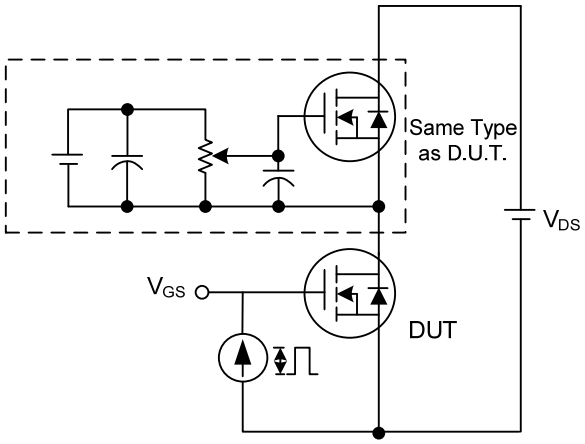
■ TEST CIRCUITS AND WAVEFORMS



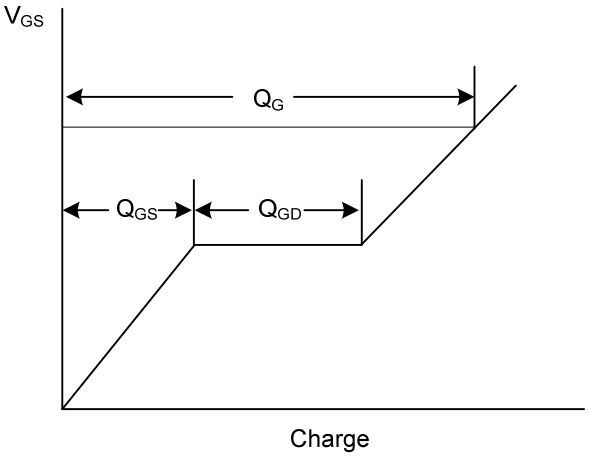
Switching Test Circuit



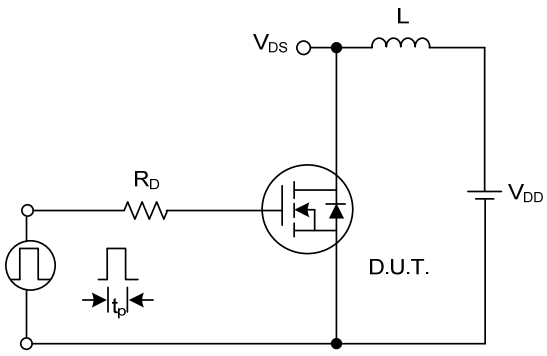
Switching Waveforms



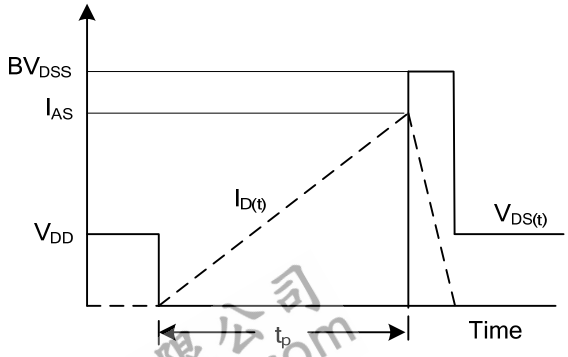
Gate Charge Test Circuit



Gate Charge Waveform



Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms

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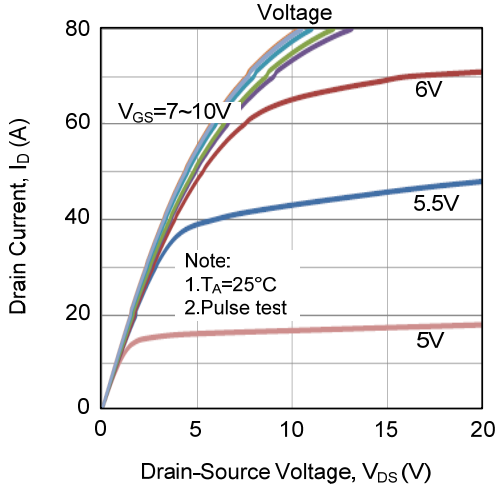
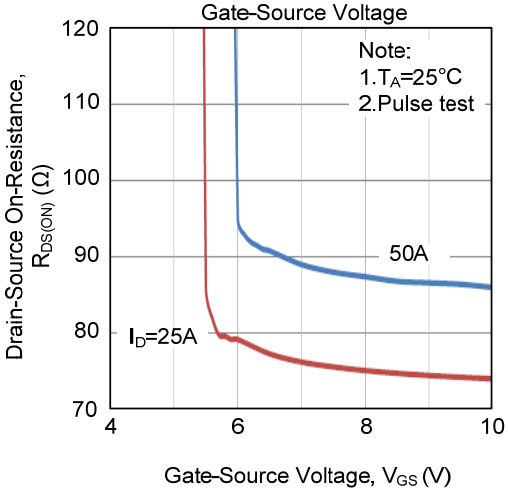
■ TYPICAL CHARACTERISTICS

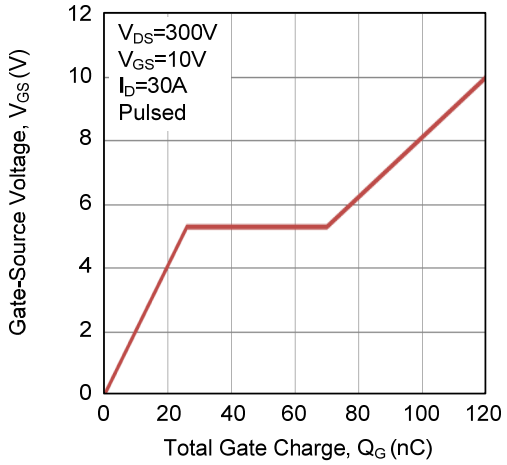
Drain Current vs. Drain-Source Voltage



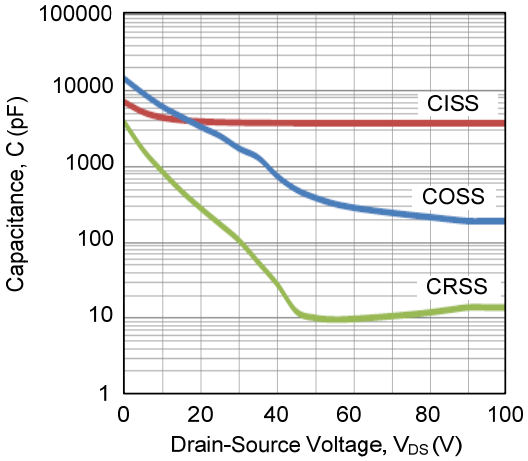
Drain-Source On-Resistance vs. Gate-Source Voltage



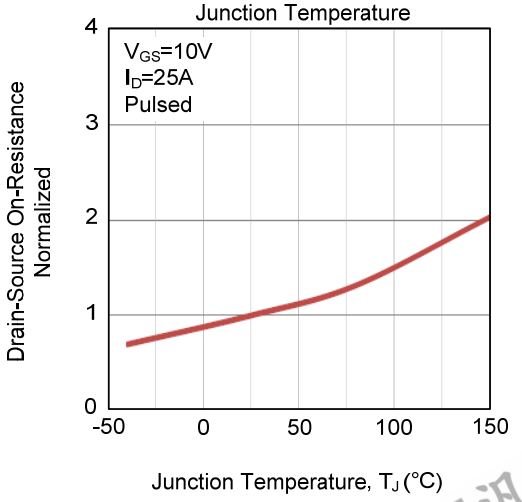
Gate Charge Characteristics



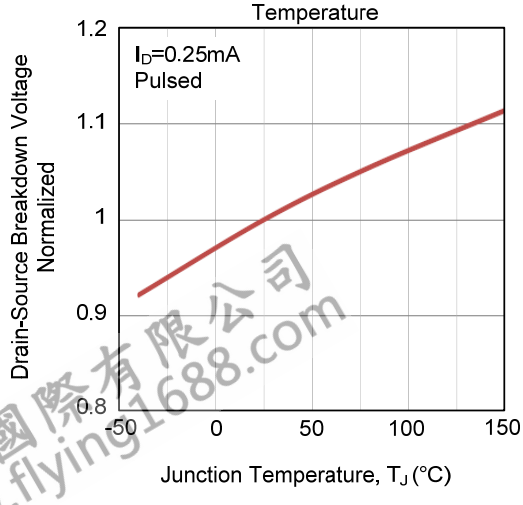
Capacitance Characteristics



Drain-Source On-Resistance vs. Junction Temperature



Breakdown Voltage vs. Junction Temperature



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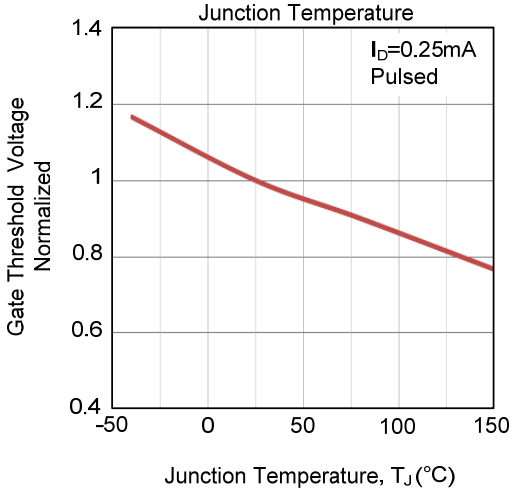
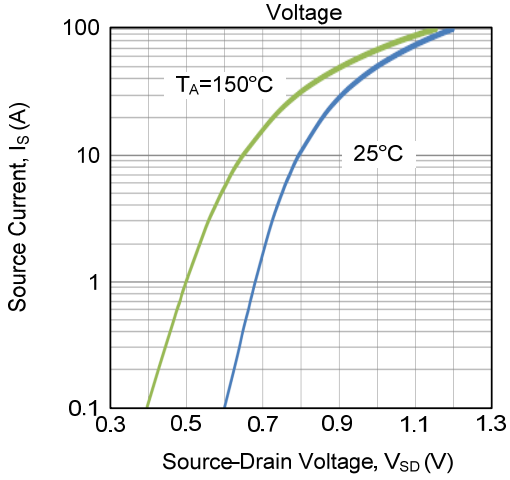
■ TYPICAL CHARACTERISTICS (Cont.)

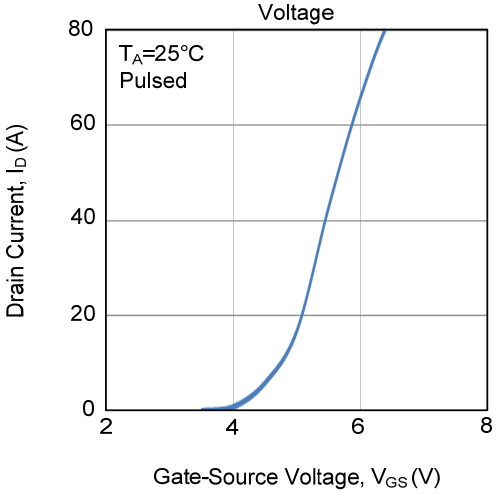
Gate Threshold Voltage vs. Junction Temperature



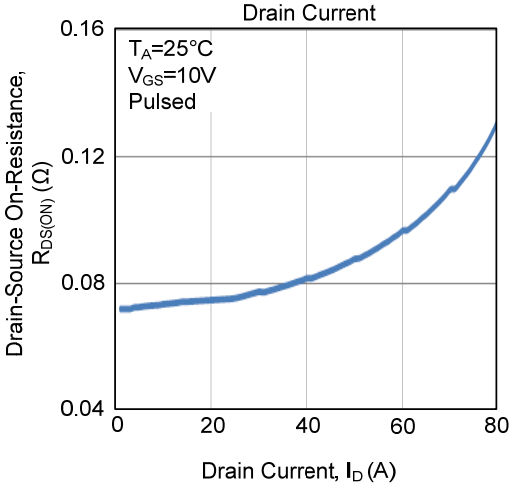
Source Current vs. Source-Drain Voltage



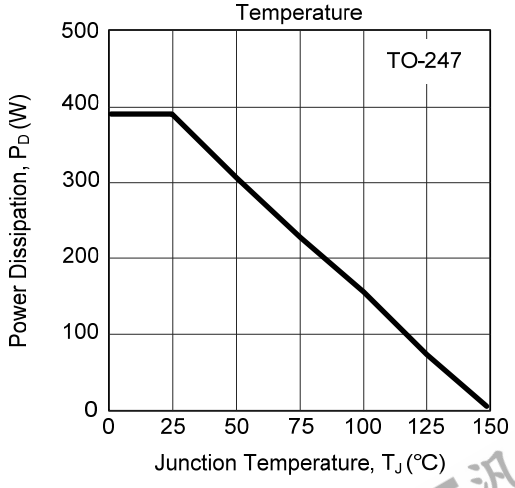
Drain Current vs. Gate-Source Voltage



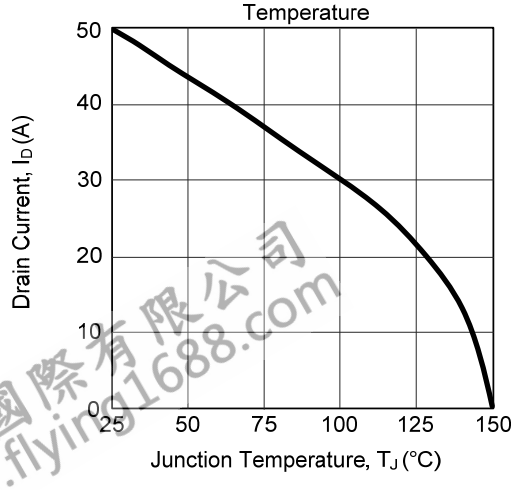
Drain-Source On-Resistance vs. Drain Current



Power Dissipation vs. Junction Temperature



Drain Current vs. Junction Temperature



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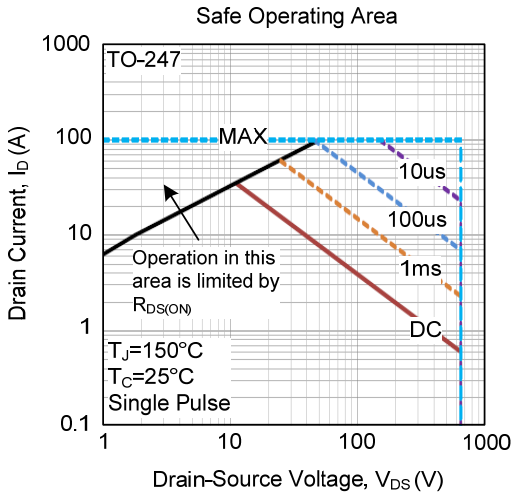
■ TYPICAL CHARACTERISTICS (Cont.)



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